L Number	Hits	Search Text	DB	Time stamp
20	206	(((zinc with copper) or (metal)) with	USPAT;	2003/04/01 17:06
1		alloy) and ((dried or drying or dry) with	US-PGPUB	
İ		<pre>(nitrogen or "N.sub.2") with gas) and ((rinse or rinsing or rinsed) with water)</pre>		
		and (electro\$6)		
21	1628	l	USPAT;	2003/04/01 17:07
21	1020	electrodeposition or electrolytic) and	US-PGPUB	
ļ		plating and (((copper with zinc) or metal)		
		with alloy) and (DI or deionized)		
22	377	(electroplating or electrochemical or	USPAT;	2003/04/01 17:14
		electrodeposition or electrolytic) and	US-PGPUB	
		plating and (copper with zinc with alloy)		
1		and (DI or deionized)		
39	22	((electroplating or electrochemical or	USPAT;	2003/04/01 17:15
1		electrodeposition or electrolytic) and	US-PGPUB	
!		plating and (copper with zinc with alloy)		
		and (DI or deionized)) and metallization		
40	239		USPAT;	2003/04/01 17:17
i		electrodeposition or electrolytic) and	US-PGPUB	
ļ		plating and (copper with zinc with alloy)		
		and ((DI or deionized) same (bath or		
		solution or mixed or mixing or dissolve or		
- 1		dissolving))		
41	47	((electroplating or electrochemical or	USPAT;	2003/04/01 17:15
į		electrodeposition or electrolytic) and	US-PGPUB	
		plating and (copper with zinc with alloy)		
İ		and ((DI or deionized) same (bath or	1	
ļ		solution or mixed or mixing or dissolve or		1
		dissolving))) and semiconductor		1000010110110
42	125		USPAT;	2003/04/01 17:27
		electrodeposition or electrolytic) and	US-PGPUB	
ļ		plating and (copper with zinc with alloy)		
		and ((DI or deionized) same (bath or		
		solution or mixed or mixing or dissolve or		
ļ		dissolving) same (salt or sulfate or ion		
	_	or cation))	110537	2003/03/27 16:32
-	1	("6515368").PN.	USPAT;	2003/03/27 10:32
i		(0.05 (0.00) 0.05 0	US-PGPUB	2003/03/27 16:39
- j	284	(205/228).CCLS.	USPAT; US-PGPUB	2003/03/2/ 10.39
	7.0	//205/000\ GGIG \ and /common on ging on	USPAT;	2003/03/27 16:39
-	78	((205/228).CCLS.) and (copper or zinc or	1	2003/03/27 10.39
	7.	Cu or Zn)	US-PGPUB	2003/03/27 17:01
-	7 4	(((205/228).CCLS.) and (copper or zinc or	USPAT; US-PGPUB	2003/03/2/ 1/.01
ļ	670	Cu or Zn)) and alloy (copper same zinc same (alloy or	USPAT;	2003/03/27 17:24
- !	5/9	combination)) same (electro\$5 with (plate	US-PGPUB	2000,00,27 17.24
ļ		or plating or solution))	35 13105	
_	120	((copper same zinc same (alloy or	USPAT;	2003/03/27 17:08
_ [120	combination)) same (electro\$5 with (plate	US-PGPUB	1 2000, 00, 2, 2, 100
		or plating or solution))) and	33 13102	
		(semiconductor or "IC" or "integrated		
		circuit")		
_	344	((copper with zinc with alloy) or ("Cu	USPAT;	2003/03/27 18:04
_	Jaa	Zn")) with ((electro\$7 with (plate or	US-PGPUB	2000, 00, 00
		plating or deposition or depositing)) or	00 10102	
1		electroplating)		
_	189	·	USPAT;	2003/03/27 18:07
_	107	Zn")) with ((electro\$7 with (plate or	US-PGPUB	
		plating or deposition or depositing)) or		
Ì		electroplating)	1	
_	303	1	USPAT;	2003/03/28 12:27
Ì	505	Zn")) with ((electro\$7 with (plate or	US-PGPUB	
İ		plating or deposition or depositing)) or		
		electroplating)) and solution		
	69		USPAT;	2003/03/28 13:07
_	09			1
-		(Rh")) With ((electros) With (blace or	1 02-56508	1
-		Zn")) with ((electro\$7 with (plate or	US-PGPUB	
-		plating or deposition or depositing)) or electroplating)) and solution) and (zinc	US-PGPUB	

				· ·
-	24	(((((copper with zinc with alloy) or ("Cu	USPAT;	2003/03/28 12:29
	; }	Zn")) with ((electro\$7 with (plate or	US-PGPUB	i
		plating or deposition or depositing)) or		
	İ	electroplating)) and solution) and (zinc		
i	1	with salt)) and (complexer or complexing)		
_	1	("6,176,996").PN.	USPAT;	2003/03/28 12:29
	İ		US-PGPUB	
-	6	("6022808" "6181012" "6197181"	USPAT	2003/03/28 12:36
1		. "6249055" "6319387" "6368966"		I •
	-	"2002/0074234").PN.		
_	! 0		USPAT	2003/03/28 12:51
! -	45		USPAT;	2003/03/28 13:07
ļ	!	Zn")) with ((electro\$7 with (plate or	US-PGPUB	
		plating or deposition or depositing)) or		
		electroplating)) and solution) and (zinc	1	1
		with salt)) not (((((copper with zinc		
		with alloy) or ("Cu Zn")) with ((electro\$7		1
	1	with (plate or plating or deposition or		
		depositing)) or electroplating)) and		1
		solution) and (zinc with salt)) and		1
		(complexer or complexing))		
_	234	((((copper with zinc with alloy) or ("Cu	USPAT;	2003/03/28 14:30
	1	Zn")) with ((electro\$7 with (plate or	US-PGPUB	
		plating or deposition or depositing)) or		
	1	electroplating)) and solution) not		
	İ	(((((copper with zinc with alloy) or ("Cu		1
		Zn")) with ((electro\$7 with (plate or		
		plating or deposition or depositing)) or		
	1	electroplating)) and solution) and (zinc		
į		with salt))		
i -	23		USPAT;	2003/03/28 14:46
		Zn")) with ((electro\$7 with (plate or	US-PGPUB	
		plating or deposition or depositing)) or		
		electroplating)) and solution) not		
		(((((copper with zinc with alloy) or ("Cu	İ	
	}	Zn")) with ((electro\$7 with (plate or		
1	1	plating or deposition or depositing)) or	ŀ	
	i	electroplating)) and solution) and (zinc		
		with salt))) and deionized	}	
-	1	("4356067").PN.	USPAT;	2003/03/31 11:46
			US-PGPUB	
_	5	(((deionized or DI) adj water) with	USPAT;	2003/03/31 11:53
į	:	(chemical or solution) with bath) and	US-PGPUB	
		electroplating and ((copper or cu) near2		
I I		(zinc or zn))		

		And the second s		
-	8		USPAT;	2003/03/31 11:50
		US-5388328-\$ or US-5217536-\$ or	US-PGPUB	1
1	i	US-6528424-\$ or US-6515368-\$ or	!	1
		US-6143160-\$ or US-4904354-\$ or]
i	1	US-4686017-\$ or US-4272570-\$ or		!
1	1	US-4075066-\$ or US-3919056-\$ or		i
		US-3930965-\$ or US-3669854-\$ or		
		US-3716462-\$ or US-6368966-\$ or		
		US-6319387-\$ or US-4036600-\$ or		ì
İ		US-4092448-\$ or US-4101386-\$ or		
	1	US-4049481-\$ or US-6528412-\$ or	!	
		US-6271589-\$ or US-6251249-\$ or		1
1	1	US-4060467-\$ or US-6342146-\$).did. or		1
1	1	(US-6235406-\$ or US-6176994-\$ or		1
	1	US-5176812-\$ or US-4465561-\$ or		1
	1	US-4441965-\$ or US-4383898-\$ or		!
ĺ	i	US-4379738-\$ or US-4104137-\$ or		
		US-4043878-\$ or US-4859289-\$ or		
		US-4814049-\$ or US-4599279-\$ or		1
		US-6197181-\$ or US-5230932-\$ or		
	1	US-5021269-\$ or US-4730022-\$ or		1
		US-4417956-\$ or US-4390377-\$ or		
1	1	US-4356067-\$ or US-4115211-\$ or]
	1	US-4076600-\$).did. or (US-20020074244-\$ or		i I
1	1	US-20010014410-\$ or US-20020175419-\$ or		
1	İ	US-20020127847-\$ or US-20020134684-\$ or		
		US-20020112965-\$ or US-20030049850-\$ or		
		US-20030010645-\$).did.) and ((DI or		
ĺ	1	deionized) near water)		
-	23		USPAT;	2003/03/31 12:30
1		electroplating) and ((copper or cu) near2	US-PGPUB	
		(zinc or zn))		
-	25	(drying with (gas) same (nitrogen)) and	USPAT;	2003/03/31 13:08
	•	electroplating and rinsing	US-PGPUB	
_	1	("5,441,629").PN.	USPAT;	2003/03/31 13:18
i			US-PGPUB	:
_	70	(electroplating with bath) same ((DI or	USPAT;	2003/03/31 13:21
İ	1	deionized) adj water)	US-PGPUB]
1	1	1		A